



FINAL PRODUCT/PROCESS CHANGE NOTIFICATION #20626BBGeneric Copy

Issue Date: 13-Oct-2014

TITLE: Final PCN for wire change from gold to copper, mold compound change and part number change.

PROPOSED FIRST SHIP DATE: starting on 13-Jan-2015 (the actual ship date will be different by each product, please check the responsible Sales person).

AFFECTED CHANGE CATEGORY(S): Assembly area- Wire Bonding and Mold compound and Part number change

FOR ANY QUESTIONS CONCERNING THIS NOTIFICATION:

Contact your local ON Semiconductor Sales Office or [Yasuhiro Igarashi@onsemi.com](mailto:Yasuhiro.Igarashi@onsemi.com)

SAMPLES: Contact your local ON Semiconductor Sales Office or [Shigehito Matsumoto@onsemi.com](mailto:Shigehito.Matsumoto@onsemi.com)

ADDITIONAL RELIABILITY DATA: Available

Contact your local ON Semiconductor Sales Office or Kazutoshi.Kitazume@onsemi.com

NOTIFICATION TYPE:

Final Product/Process Change Notification (FPCN)

Final change notification sent to customers. FPCNs are issued at least 90 days prior to implementation of the change.

ON Semiconductor will consider this change approved unless specific conditions of acceptance are provided in writing within 30 days of receipt of this notice. To do so, contact [<quality@onsemi.com>](mailto:quality@onsemi.com).

DESCRIPTION AND PURPOSE:

This is a Final Process Change Notification to announce for below contents.

- 1) Changing wire material from gold to copper
- 2) Changing part number from XXXXXX-TL-H or XXXXXX-TL-E to XXXXXX-TL-W.
(See the list of models)
- 3) Changing mold compound from halide to halide free, in case of changing from XXXXXX-TL-E to XXXXXX-TL-W.
There is no change in case of changing from XXXXXX-TL-H to XXXXXX-TL-W.

The product design and electrical specifications will remain identical. A full electrical characterization over the temperature range will be performed for each product to check the device functionality and electrical specifications. Qualification tests are designed to show that the reliability of transferred devices will continue to meet or exceed ON Semiconductor standards.



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RELIABILITY DATA SUMMARY:

Reliability Test Results:

Test	Conditions	Results	
Steady State Operating Life	Tj=150degC	1000 hrs	Pass
High Temperature Reverse Bias	Ta=150degC, VR=max	1000 hrs	Pass
Temp Humidity Storage	Ta=85degC, RH=85%	1000 hrs	Pass
Temperature Cycle	Ta=-55degC to 150degC 30min each	100 cycles	Pass
Pressure Cooker	Ta=121degC, 2.03 × 10 ⁵ Pa, 100%	50 hrs	Pass
High Temperature Storage	Ta=150degC	1000 hrs	Pass
Resistance to Soldering heat (Reflow)	Solder Temp.: 260degC ± 5degC	10s	Pass
Solderability	Solder Temp.: 245degC ± 5degC	5 s	Pass

ELECTRICAL CHARACTERISTIC SUMMARY:

There is no change in the electrical performance. Datasheet specifications remain unchanged.

CHANGED PART IDENTIFICATION:

PART_ID	New PART_ID
CPH3350-TL-H	CPH3350-TL-W

List of affected General Parts:

PART_ID
CPH3350-TL-H